Title (en)

METHOD FOR PRODUCING A FLOOR COVERING SUBSTRATE AND FLOORING COMPRISING AT LEAST ONE ELECTRONIC CONSTRUCTION ELEMENT INTEGRATED THEREIN

Title (de)

VERFAHREN ZUM HERSTELLEN EINER BODENBELAGUNTERLAGE UND FUSSBODEN MIT MINDESTENS EINEM DARIN INTEGRIERTEN ELEKTRONISCHEN BAUELEMENT

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE SOUS-COUCHE DE REVÊTEMENT DE SOL ET SOL DANS LEQUELLE EST INTÉGRÉ AU MOINS UN COMPOSANT ÉLECTRONIQUE

Publication

EP 2247780 B1 20150916 (DE)

Application

EP 09713359 A 20090220

Priority

• EP 2009052072 W 20090220
• DE 102008010530 A 20080222

Abstract (en)

[origin: WO2009103806A2] In a method for producing a floor covering substrate, at least one electronic construction element is embedded in a layer comprising at least one curable material. In a method for producing a substrate layer for a floor covering substrate, a substrate layer is provided wherein the substrate layer comprises a permeable structure or a mesh structure. Further, at least one electronic construction element is disposed in the substrate layer and/or applied to the substrate layer.

IPC 8 full level

D06N 7/00 (2006.01); **E04F 15/12** (2006.01); **E04F 15/16** (2006.01)

CPC (source: EP US)

D06N 7/0089 (2013.01 - EP US); **E04F 15/12** (2013.01 - EP US); **E04F 15/185** (2013.01 - EP US); Y10T 156/10 (2015.01 - EP US); Y10T 156/1064 (2015.01 - EP US); Y10T 156/109 (2015.01 - EP US); Y10T 428/239 (2015.01 - EP US); Y10T 428/24612 (2015.01 - EP US); Y10T 428/249921 (2015.04 - EP US); Y10T 428/249953 (2015.04 - EP US); Y10T 428/2848 (2015.01 - EP US); Y10T 442/10 (2015.04 - EP US)

Citation (examination)

US 6434328 B2 20020813 - RUTHERFORD JAMES M [US]

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DOCDB simple family (publication)

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